

Title (en)
MICROELECTRONIC BONDING WITH LEAD MOTION

Title (de)
MIKROELEKTRONISCHE BONDVERBINDUNG MIT LEITERBEWEGUNG

Title (fr)
FIXATION MICRO-ELECTRONIQUE AVEC MOUVEMENT DES CONDUCTEURS

Publication
EP 0800753 A4 20010117 (EN)

Application
EP 95932549 A 19950919

Priority
• US 9511899 W 19950919
• US 30874194 A 19940919

Abstract (en)
[origin: US5491302A] A method of connecting a semiconductor chip assembly having at least first and second contacts to a connection component including at least first and second connection leads by means of a tool consisting of the steps of juxtaposing moving and connecting the leads to the corresponding contacts. The connection component is juxtaposed with the semiconductor chip assembly so that the first and second connection leads are aligned with the first and second contacts in such a manner that the first connection lead is offset from the first contact in the first direction and the second connection lead is offset from the second contact in the same first direction. The first connection lead is moved by means of the tool substantially downwardly and towards the first contact in a second direction which is opposite to the first direction, so that an open space is formed between the first connection lead and the second contact and lead to facilitate movement of the second connection lead by the tool substantially downwardly and towards the second contact in the second direction.

IPC 1-7
H05K 1/00; **H01L 21/00**

IPC 8 full level
H01L 21/60 (2006.01); **H01L 21/00** (2006.01); **H01L 21/607** (2006.01); **H05K 3/32** (2006.01); **H05K 13/04** (2006.01)

CPC (source: EP KR US)
H01L 21/67144 (2013.01 - EP US); **H01L 24/50** (2013.01 - EP US); **H01L 24/86** (2013.01 - EP US); **H05K 1/00** (2013.01 - KR); **H01L 2924/01004** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US); **H01L 2924/01006** (2013.01 - EP US); **H01L 2924/01015** (2013.01 - EP US); **H01L 2924/01023** (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US); **H01L 2924/01079** (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **Y10T 29/4913** (2015.01 - EP US); **Y10T 29/49135** (2015.01 - EP US)

Citation (search report)
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• [A] US 5091825 A 19920225 - HILL WILLIAM H [US], et al
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• [A] US 5153981 A 19921013 - SOTO VICENTE [US]
• [A] WO 9403036 A1 19940203 - TESSERA INC [US], et al
• [A] PATENT ABSTRACTS OF JAPAN vol. 015, no. 114 (E - 1047) 19 March 1991 (1991-03-19)

Designated contracting state (EPC)
AT BE CH DE DK ES FR GB GR IE IT LI LU MC NL PT SE

DOCDB simple family (publication)
US 5619017 A 19970408; AT E256378 T1 20031215; AU 3555995 A 19960409; DE 69532298 D1 20040122; DE 69532298 T2 20040916; EP 0800753 A1 19971015; EP 0800753 A4 20010117; EP 0800753 B1 20031210; JP 2005101638 A 20050414; JP 3658407 B2 20050608; JP 3822892 B2 20060920; JP H10506235 A 19980616; KR 100334990 B1 20020620; KR 970706712 A 19971103; US 5491302 A 19960213; WO 9609745 A1 19960328

DOCDB simple family (application)
US 55145895 A 19951101; AT 95932549 T 19950919; AU 3555995 A 19950919; DE 69532298 T 19950919; EP 95932549 A 19950919; JP 2004325234 A 20041109; JP 51102896 A 19950919; KR 19970701646 A 19970313; US 30874194 A 19940919; US 9511899 W 19950919